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THz radiation emission properties of multienergy arsenic-ion-implanted GaAs and semi-insulating GaAs based photoconductive antennas

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We compare the performance of THz photoconductive (PC) emitter antennas fabricated on multienergy arsenic ion implanted GaAs (multi-GaAs:As⁺) and semi-insulating GaAs. High damage threshold biasing (>60 kV/cm) and large saturation optical-pumping power (~20 mW) for multi-GaAs:As⁺ based PC antennas are reported. Carrier mobility in the As ion implanted layer of GaAs:As⁺ was estimated to be about 150 cm²/Vs, which was comparable to that of low temperature GaAs.

I. INTRODUCTION

Low-temperature (LT) grown GaAs is widely used as the photoconductive (PC) substrate of PC antennas for generation and detection of THz radiation because of the high-resistivity (10⁷ Ω cm)³ and reasonably good mobility (100–300 cm²/Vs), in addition to the short carrier lifetime (~1 ps). Recently, an alternative material was reported to be promising as the substrate material of PC antennas, that is, the arsenic ion implanted GaAs (designated as `GaAs:As⁺' hereafter). Since the GaAs:As⁺ exhibits structural, electrical, and ultrafast optoelectronic characteristics strikingly similar to those of LT GaAs, it can be an alternative to LT GaAs for THz PC antennas.

Preparation of PC substrates by ion implantation has several advantages against the LT growth of GaAs. Ion dosage can be precisely and reproducibly controlled, and hence the properties of the ion implanted substrate can be also reproducible. On the other hand, the absolute epipetal growth temperature of GaAs, which is the most important parameter to the property of LT GaAs, is difficult to control due to lack of a reliable temperature monitoring method at the low growth temperature range (<400 °C). Therefore, LT GaAs properties are not assured to be the same from furnace to furnace even though the same nominal growth parameters were used. In addition, it was reported that the long nonexponential tailing in photoexcited carrier decay, which is commonly observed for LT GaAs, is eliminated at high ion dosages, which is expected to enable a faster PC response of the ion-implanted GaAs antennas. After annealing, it shows a high breakdown voltage comparable to LT GaAs, suggesting a high emission efficiency for generating THz radiation by applying a larger electric bias field.

II. EXPERIMENTAL METHODS

For SI GaAs devices, we employed liquid encapsulated Czochralski grown SI (100) GaAs as substrates. The GaAs:As⁺ samples were prepared by first bombarding SI GaAs substrates with arsenic ions at doses of 10¹⁶ ions/cm² and ion energies of 150 and/or 200 keV. A commercial ion implanter (Varian E220) was used. This is followed by furnace annealing at 600 °C for 30 min, with flowing N₂ gas and encapsulation. The ion implantation depth was estimated to be about 100 nm by secondary ion mass spectroscopy measurement. For simplicity, samples implanted with ions of two energies are referred to as multi-GaAs:As⁺, while we refer to single-GaAs:As⁺ for samples implanted with ions of one energy. The structure of the photoconductive dipole antenna is shown in Fig. 1. The antenna length L, width W, photoconductive gap G, and transmission linewidth D are 10 m, 20, 5, and 20 μm, respectively. The experimental setup was a PC emitter–detector system similar to that reported in Ref. 1. The detector was a PC dipole antenna fabricated on a LT GaAs substrate (grown by the molecular beam epitaxy at 250 °C and annealed at 600 °C for 5 min after the growth), whose dimensions were L = 20 μm, W = 10 μm, G = 5 μm, and D = 5 μm. The carrier lifetime was estimated to be 0.3

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Laser Excitation

![Schematic diagram of the PC antenna.](image)

FIG. 1. Schematic diagram of the PC antenna.

ps by a transient photoreflectance measurement. Pumping source for the emitter and receiver antenna was a mode-locked Ti:sapphire laser, which produced 80 fs light pulses at a wavelength of 780 nm and a repetition rate of 82 MHz. A Si hemispherical substrate lens was used for the receiver antenna, while no lens was used for the emitter antennas. Irradiated average power and applied voltage were varied from 0 to about 30 mW and 30 V, respectively. Probe beam power was around 2.5 mW. Figure 2 shows the current–voltage (I–V) curves measured for 20 μm gaps of multi-GaAs:As$^+$ (ion energies of 150 and 200 keV) and single-GaAs:As$^+$ (ion energy of 200 keV) with the furnace annealing, and also for the same gap of SI GaAs. The dark current characteristic of the SI GaAs, multi- (ion energies of 150 and 200 keV), single-ion implanted GaAs (ion energy of 200 keV) are compared in Table I. Samples used in these measurements had coplanar waveguide type electrodes, and were applied with bias voltages of 30 and 60 V. The annealing process reduced the dark currents of the ion-implanted GaAs to a level (less than or equal to 0.5 nA at a bias of 30 V), which was much lower than that of SI GaAs. After annealing, the carrier transport mechanism was changed from hopping conduction to thermal emission, corresponding to the reduction in the trapping site density. The antisite defect density was reported to be reduced to about 2 orders of magnitude lower than that of as-implanted materials. The high resistivity after annealing is attributed to the formation of arsenic precipitates, which is accompanied by recovery of crystallinity and hence an increase of the carrier mobility. The dark I–V characteristics of the single-, multi-GaAs:As$^+$ samples were similar, although the dark current of the multi-GaAs:As$^+$ was slightly lower than that of the single-GaAs:As$^+$. The more uniform distributions of arsenic precipitation in the multi-GaAs:As$^+$ sample might be better for the high resistivity. Such a low dark current level in the high bias region implies that the multi, or single ion-implanted GaAs can sustain much higher bias electric field than SI GaAs, and thus can increase the emission efficiency of THz radiation.

### III. RESULTS AND DISCUSSIONS

#### A. Wave forms and spectra

The THz wave forms emitted from the multi-GaAs:As$^+$ (solid curve) and the SI GaAs (dash curve) dipole antenna are shown in Fig. 3(a). The applied bias voltage and pumping power were about 10 V and 5 mW, respectively. The wave form of the multi-GaAs:As$^+$ antenna was normalized at the main peak amplitude in the wave form of the SI GaAs antenna. We observe a clear difference between the two wave forms: the minimum peak after the main peak is sharper and bigger than that for the SI GaAs antenna, while the minimum peak before the main peak decreased compared to that of the SI GaAs antenna. Reflecting this difference, the Fourier transformed spectrum of the wave form for the multi-GaAs:As$^+$ antenna is shifted to a higher frequency region compared to that of the SI GaAs antenna [Fig. 3(b)]. The frequency at the spectrum peak for the GaAs:As$^+$ antenna is 0.9 THz, while it is 0.7 THz for the SI GaAs antenna, and the full width at half maximum (FWHM) bandwidth of the spectrum distribution is about 1.2 THz. To explain the observed difference in the wave forms of the THz radiation emitted from the two antennas, we need to consider the carrier dynamics in each photoconductive substrate.

In order to interpret the THz radiation wave form, we use the dipole radiation approximation, where the emitted field is assumed to be proportional to the time derivative of the transient current $J(t)$ at far field: $E_{THz}(t) \propto \partial J(t)/\partial t$. In this approximation the main (positive) peak observed in the wave forms in Fig. 3(a) is attributed to the rises of the surge current by the photocarrier injection and the subsequent carrier acceleration under the bias field in the PC antennas, while the second negative peak preceded by the main peak is attributed to the decay of the current governed by the carrier trapping times. The origin of the first negative peak before the main peak is attributed to the pulse reshaping effect due

### TABLE I. Comparison of dark current between SI-GaAs, multi- and single-ion implanted GaAs.

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<tbody>
<tr>
<td></td>
<td>GaAs</td>
<td>anneal 30 min</td>
<td>anneal 60 min</td>
<td>anneal 30 min</td>
<td>anneal 60 min</td>
<td>anneal 30 min</td>
</tr>
<tr>
<td>Bias</td>
<td>18 nA</td>
<td>3.83 μA</td>
<td>0.05 nA</td>
<td>0.13 nA</td>
<td>0.29 nA</td>
<td>0.52 nA</td>
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<tr>
<td>30 V</td>
<td>Breakdown</td>
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<td>0.15 nA</td>
<td>0.28 nA</td>
<td>1.2 nA</td>
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to the frequency dependent THz beam focus on the detector antenna, which gives rise to an equivalent effect of a high-pass filter to the THz radiation.\textsuperscript{14,15}

For the GaAs:As\textsuperscript{+} antenna, we have to consider the carrier dynamics in the ion implanted layer and also in the SI GaAs substrate layer beneath because the optical penetration depth ($\sim$1 $\mu$m) of the infrared laser light is larger than the ion implanted layer ($\sim$100 nm) and, hence, a significant amount of carriers are excited in the SI GaAs layer. If the pump laser pulse width ($\delta t$) is larger than the carrier momentum relaxation time ($\tau_m$), and if the carrier lifetime ($\tau_c$) is larger than the pump laser pulse width ($\tau_m < \delta t < \tau_c$), the current rise is determined by the pump laser pulse width. This is exactly the situation in our experimental condition, where the momentum relaxation time was estimated to be about 30 fs, the laser pulse width was 80 fs, and the carrier lifetime was $\sim$0.3 ps in the ion implanted layer or $>100$ ps in the SI GaAs layer, respectively. Therefore, the carriers in both layers contribute to the current rise in the same way after the excitation in the GaAs:As\textsuperscript{+} antenna. However, because the carrier decay time in the ion-implanted layer is shorter than that in the SI GaAs layer, the carriers in the SI GaAs layer are blocked by the ion-implanted layer, which returns the original insulating state after the fast carrier decay. Therefore, we can conclude that the transient current in the GaAs:As\textsuperscript{+} antenna is governed by the carrier dynamics in the ion implanted layer. This model explains the sharp negative peak after the main peak and the resultant spectrum shift to the higher frequency side, which is attributed to the fast current decay in the ion implanted layer.

Figures 4(a) and 4(b) show the THz radiation wave forms and spectrums for the SI GaAs dipole antenna at various bias voltages (1, 5, 10, 15, and 20 V). The wave forms were normalized at their main peak amplitudes. The main peak amplitude increased linearly with the bias voltage, and the second negative peak amplitude changed nonlinearly depending on the bias. The inset in Fig. 4(a) shows the bias dependence of the amplitude at the negative peak. In addition, we can see that the positive main peak shifts slightly to the earlier time delay with the increase in bias. Similar behavior was also observed for the case of multi-GaAs:As\textsuperscript{+}.\textsuperscript{16,17}
shown in Fig. 5(a), although the relative change in the second negative peak was much smaller [The inset in upper part of Fig. 5(a) shows the bias dependence of the amplitude at the negative peak.] The spectral peak was shifted from 0.7 to 0.9 THz for the SI GaAs antenna when the bias was increased from 5 to 20 V as shown in Fig. 4(b). On the other hand, there was no significant change in the center frequency (~0.9 THz) for the GaAs:As⁺ antenna as shown in Fig. 5(b). Bandwidth was also broadened significantly in the case of SI GaAs with the increase of the bias, while the bandwidth change for the GaAs:As⁺ was slight. These features are clearly shown in Fig. 6, where the bias dependent pulse width of the main peak (FWHM) and the time shift of the peak position were plotted for the SI GaAs antenna [Fig. 6(a)] and the GaAs:As⁺ antenna [Fig. 6(b)].

The phenomena of increasing amplitude at the negative peak and the shift of the wave form to earlier time delay is explained by the scattering of photoexcited electrons from the high mobility Γ valley to the low-mobility L valley under the bias field, as was explained for the case of LT GaAs PC antennas in Ref. 16. The higher the bias field, the faster the acceleration and scattering of electrons to the L valley, resulting in the wave form shift to the earlier time delay and more efficient deceleration of electrons (which gives rise to a larger negative peak amplitude in the wave form). This intervalley scattering effect is expected to be more significant in SI GaAs because of the longer carrier lifetime, while the carriers in the ion implanted GaAs could not have enough time to be scattered to the L valley because of the short carrier lifetime (~0.3 ps).

B. Emission efficiency

Figure 7(a) shows the bias field dependence of the peak amplitude of THz wave form for the 5 mm gap photoconductive antennas on SI GaAs and GaAs:As⁺ with a pumping power of 5 mW. The GaAs:As⁺ antenna showed a higher breakdown voltage threshold (~60 kV/cm) than for the SI GaAs antenna (~45 kV/cm). The higher breakdown voltage is an advantage of GaAs:As⁺ antennas against SI GaAs since a higher bias means a better THz radiation emission efficiency. Beyond 25 kV/cm bias field, THz radiation amplitude emitted from the GaAs:As⁺ antenna was larger than that of the SI GaAs antenna with a pump power of 20 mW even though the pump power for the GaAs:As⁺ antenna was only 5 mW.
and saturation power for the PC antenna, which depend on
the carrier mobility in the PC material. Theoretical curves
fitted to the experimental data for these two PC antennas are
shown in Fig. 7(b) by dashed lines. The agreements between
the theoretical curves and the experimental results are very
good in both cases. The characteristic saturation intensity $P_0$
for GaAs:As$^+$ ($\sim 20$ mW) is much higher than that of SI
GaAs ($\sim 6$ mW), and similar to that of LT GaAs.1 Because
the saturation power is proportional to the inverse of the
carrier mobility,17 we can estimate the relative mobility of
GaAs:As$^+$ to that of SI GaAs. If we assume the electron
mobility of SI GaAs is about $5000$ cm$^2$/V s, the effective
carrier mobility for GaAs:As$^+$ substrate is estimated to be
about $1500$ cm$^2$/V s. When we take into account the fact that
the carriers excited in the layer of the As ion implanted re-
gion is only about 10% of the total carriers, while others are
excited in the SI GaAs substrate region, the value of carrier
mobility in the As ion rich layer is estimated to be about $150$
cm$^2$/V s, which is comparable to the reported value of mo-
bility in LT GaAs ($\sim 200$ cm$^2$/V s).2

IV. CONCLUSIONS

In summary, we showed that the THz radiation wave
forms of ion-implanted GaAs:As$^+$ PC antennas were bipolar and exhibited a sharper and deeper negative second peak
than in the case of the SI GaAs antenna. We attributed this
wave form characteristic to the ultrafast carrier decay in
GaAs:As$^+$. Bias dependent wave forms of the GaAs:As$^+$
and SI GaAs antennas were explained by the $L$-valley scat-
ering of electrons, which should have been less significant
for the GaAs:As$^+$ due to the short carrier lifetime. The bi-
polar wave form of the GaAs:As$^+$ antennas resulted in a spec-
tral distribution shifted to a higher frequency. Other advan-
tages of the GaAs:As$^+$ based PC antenna are the high
damage threshold biasing ($\sim 60$ kV/cm) and the large satu-
rating optical pumping power ($\sim 20$ mW) compared to those
of the SI GaAs based antennas (bias $<45$ kV/cm and satu-
ration power $\sim 6$ mW). From the relative saturation depen-
dence on the pump power to that of the SI GaAs antenna, the
carrier mobility in the As ion implanted layer of GaAs:As$^+$
was estimated, including the SI GaAs substrate effect, to be
about $150$ cm$^2$/V s, which was comparable to that of LT
GaAs. However, the emission efficiency might be better
compared to LT GaAs based antennas because of the higher
effective mobility of $1500$ cm$^2$/V s in GaAs:As$^+$/SI GaAs
substrate. With the higher bias field and larger pumping
power confirmed in this study, GaAs:As$^+$ is promising as the
substrate of the PC emitter antennas for THz radiation.

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